

## P-Channel 20-V(D-S) MOSFET

- $V_{DSS} = -20\text{ V}$     $I_D = -2.8\text{ A}$
- $R_{DS(on)} < 114\text{ m}\Omega @ V_{GS} = -4.5\text{ V}$
- $R_{DS(on)} < 142\text{ m}\Omega @ V_{GS} = -2.5\text{ V}$

PIN2 D

PIN3 S

PIN1 G

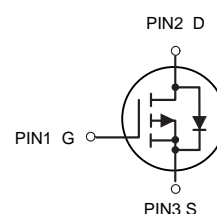
## FEATURE

- TrenchFET Power MOSFET

## APPLICATION

- Load Switch for Portable Devices
- DC/DC Converter

## SOT23

Maximum ratings ( $T_a = 25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	
Continuous Drain Current	$I_D$	-2.8	A
Pulsed Drain Current	$I_{DM}$	-10	
Continuous Source-Drain Diode Current	$I_S$	-0.72	
Maximum Power Dissipation	$P_D$	0.35	W
Thermal Resistance from Junction to Ambient( $t \leq 5\text{s}$ )	$R_{\theta JA}$	357	$^\circ\text{C/W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55 ~ +150	

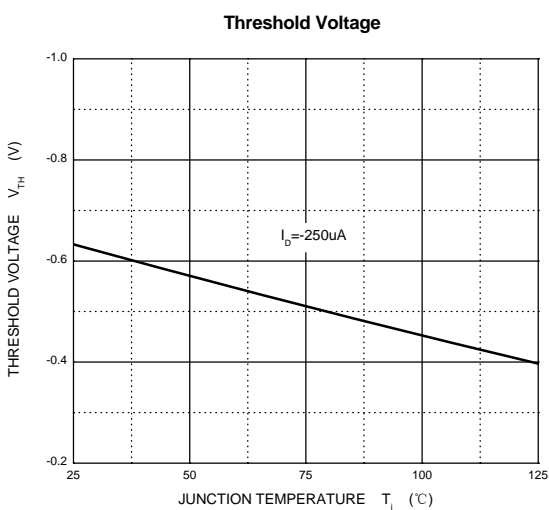
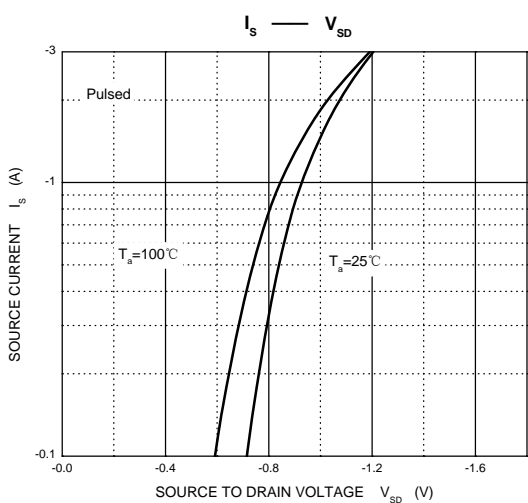
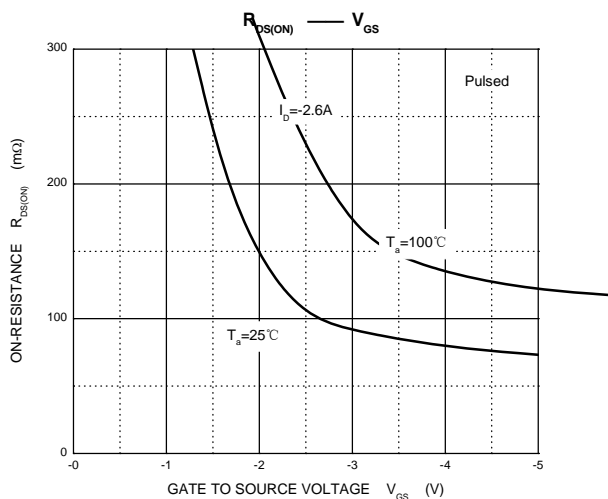
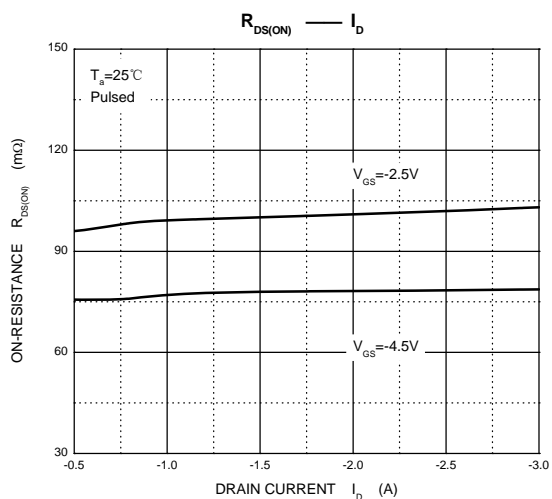
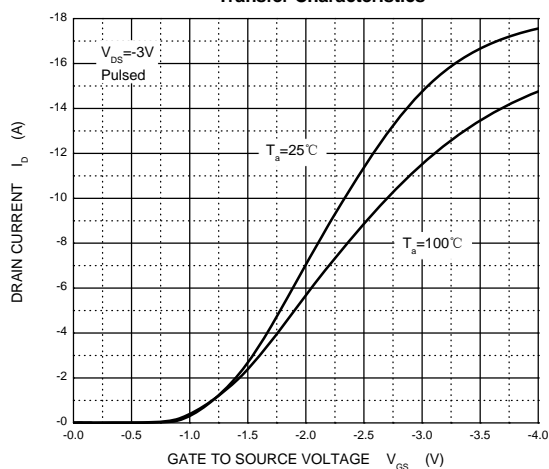
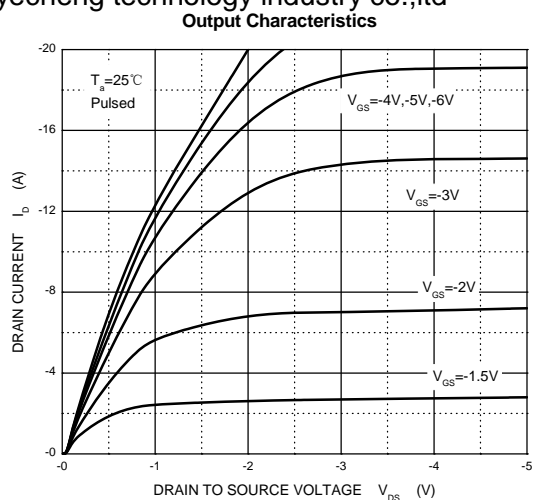
**T<sub>a</sub>=25 °C unless otherwise specified**

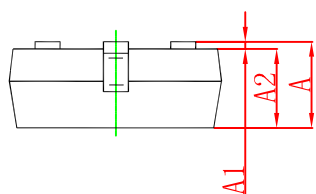
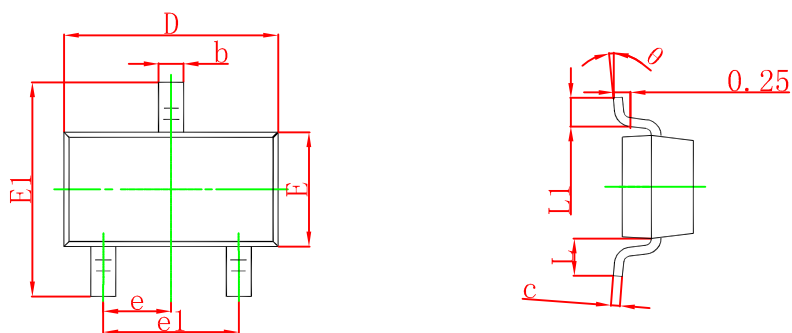
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Static</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-20			V
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.4		-1	
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±8V			±100	nA
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V			-1	μA
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -2.6A		0.086	0.114	Ω
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -2.0A		0.115	0.142	
Forward transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -2.8A		6.5		S
<b>Dynamic<sup>b</sup></b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -10V, V <sub>GS</sub> = 0V, f = 1MHz		405		pF
Output capacitance	C <sub>oss</sub>			75		
Reverse transfer capacitance	C <sub>rss</sub>			55		
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> = -10V, V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3A		5.5	10	nC
				3.3	6	
Gate-source charge	Q <sub>gs</sub>	V <sub>DS</sub> = -10V, V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -3A		0.7		
Gate-drain charge	Q <sub>gd</sub>			1.3		
Gate resistance	R <sub>g</sub>	f = 1MHz		6.0		Ω
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = -10V, R <sub>L</sub> = 10Ω, I <sub>D</sub> = -1A, V <sub>GEN</sub> = -4.5V, R <sub>g</sub> = 1Ω		11	20	ns
Rise time	t <sub>r</sub>			35	60	
Turn-off delay time	t <sub>d(off)</sub>			30	50	
Fall time	t <sub>f</sub>			10	20	
<b>Drain-source body diode characteristics</b>						
Continuous source-drain diode current	I <sub>S</sub>	T <sub>C</sub> = 25°C			-1.3	A
Pulse diode forward current <sup>a</sup>	I <sub>SM</sub>				-10	
Body diode voltage	V <sub>SD</sub>	I <sub>S</sub> = -0.7A		-0.8	-1.2	V

**Notes :**

a. Pulse Test : Pulse Width &lt; 300μs, Duty Cycle ≤ 2%.

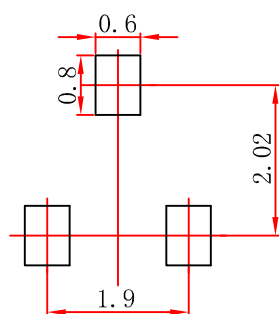
b. Guaranteed by design, not subject to production testing.





Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

**SOT-23 Suggested Pad Layout**



Note:  
 1. Controlling dimension: in millimeters.  
 2. General tolerance: ± 0.05mm.  
 3. The pad layout is for reference purposes only.